

F	2018-4				
G	2018-10-22				
H	2019-1-09	1			
I	2019-6-13		取消 <a href="#">RDSON@-20V/-10A</a> 的项目		
J	2022-1-10		VGSS=±20V 改为±25V; 特征栏和IGSS中VGSS=±20V改为±25V; 极限参数中删除 E 描述。	10.56 0 0 10.56 0 0 Tm 69.4T 184 33	

### / Descriptions

SOP-8 塑封封装 P 沟道 MOS 场效应管。  
P-Channel Enhancement Mode Field Effect Transistor in a SOP-8 Plastic Package.

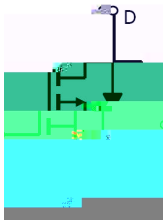
### / Features

$V_{DS} (V) = -30V$   
 $I_D = -12 A (V_{GS} = \pm 25V)$   
 $R_{DS(ON)} < 14m (V_{GS} = -10V)$   
无卤产品。HF Product.

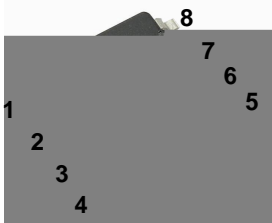
### / Applications

用于电源管理，便携式设备和电池供电系统。  
Power Management in Notebook computer, Portable Equipment and Battery powered systems.

### / Equivalent Circuit



### / Pinning



PIN 1 : S    PIN 2 : S    PIN 3 : S    PIN 4 : G  
PIN 5 : D    PIN 6 : D    PIN 7 : D    PIN 8 : D

### / Marking

见印章说明 See Marking Instructions.

**/ Absolute Maximum Ratings(Ta=25 )**

Parameter	Symbol	Rating	符 号 值 Unit
Drain-Source Voltage	$V_{DSS}$	-30	V
Gate-Source Voltage	$V_{GSS}$	$\pm 25$	V
Continuous Drain Current <sup>A</sup>	$I_D (T_a=25^\circ C)$	-12	A
Continuous Drain Current <sup>A</sup>	$I_D (T_a=70^\circ C)$	-10	A
Pulsed Drain Current <sup>B</sup>	$I_{DM}$	-60	A
Power Dissipation for Single Operation <sup>A</sup>	$P_D (T_a=25^\circ C)$	3	W
Power Dissipation for Single Operation <sup>A</sup>	$P_D (T_a=100^\circ C)$	2.1	W
Maximum Junction Temperature	$T_j$	150	$^\circ C$
Storage Temperature Range	$T_{stg}$	-55 150	$^\circ C$
Thermal Resistance-Junction to Ambient <sup>A</sup>	$R_{JA} \ t \leq 10s$	40	$^\circ C/W$
Thermal Resistance-Junction to Ambient <sup>A</sup>	$R_{JA}$	75	$^\circ C/W$
Maximum Junction-to-Lead <sup>C</sup>	$R_{JL}$	30	$^\circ C/W$

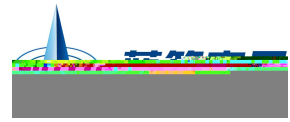
Note:

A: The value of  $R_{JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ C$ . The value in any given application depends on the user's specific board design. The current rating is based on the t 10s thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C. The  $R_{JA}$  is the sum of the thermal impedance from junction to lead  $R_{JL}$  and lead to ambient.

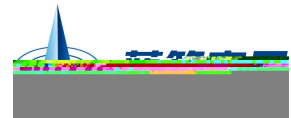
D. The static characteristics in Figures 1 to 6,12,14 are obtained using 80  $\mu s$  pulses, duty cycle 0.5% max.



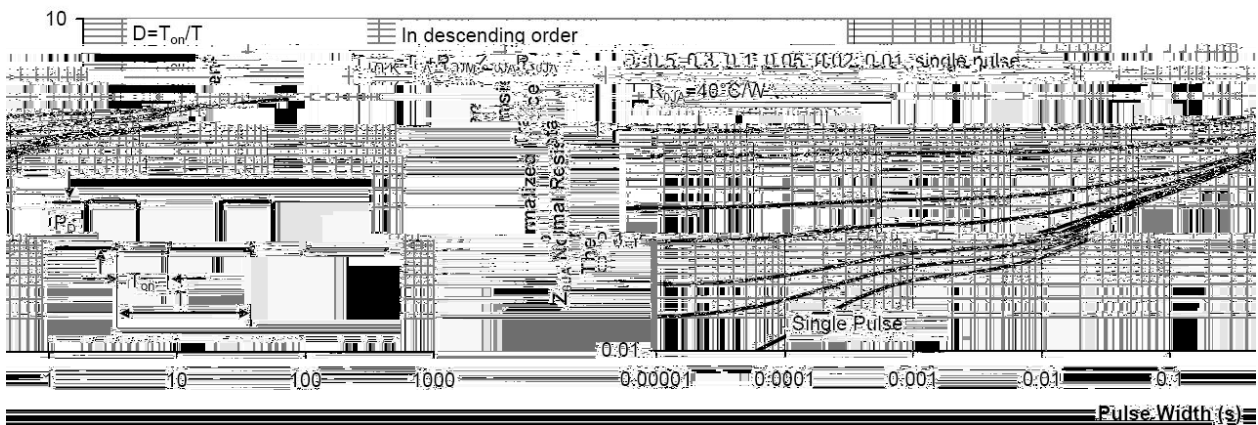
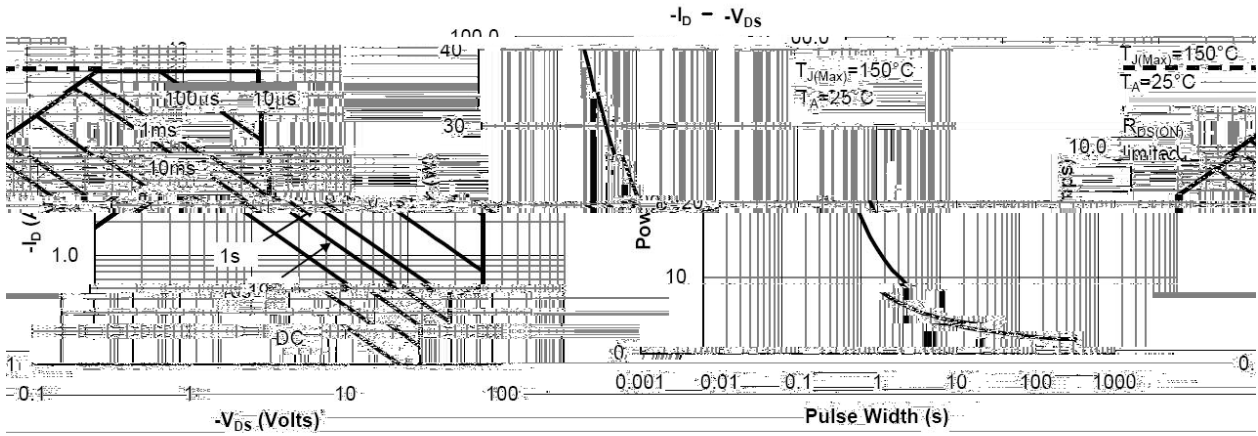
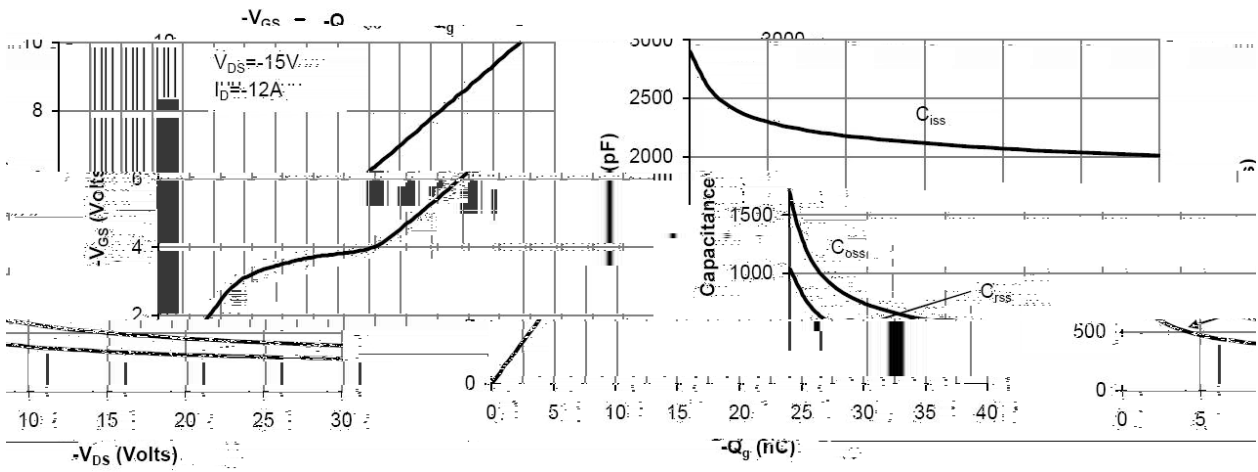
Parameter	Symbol	Test Conditions	试 Min	符 Typ	符 Max	符
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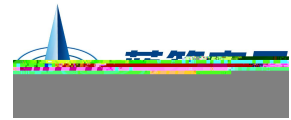
**BR4407**  
Rev.J Jan.-2022

**DATA SHEET**



/ Electrical Characteristic Curve

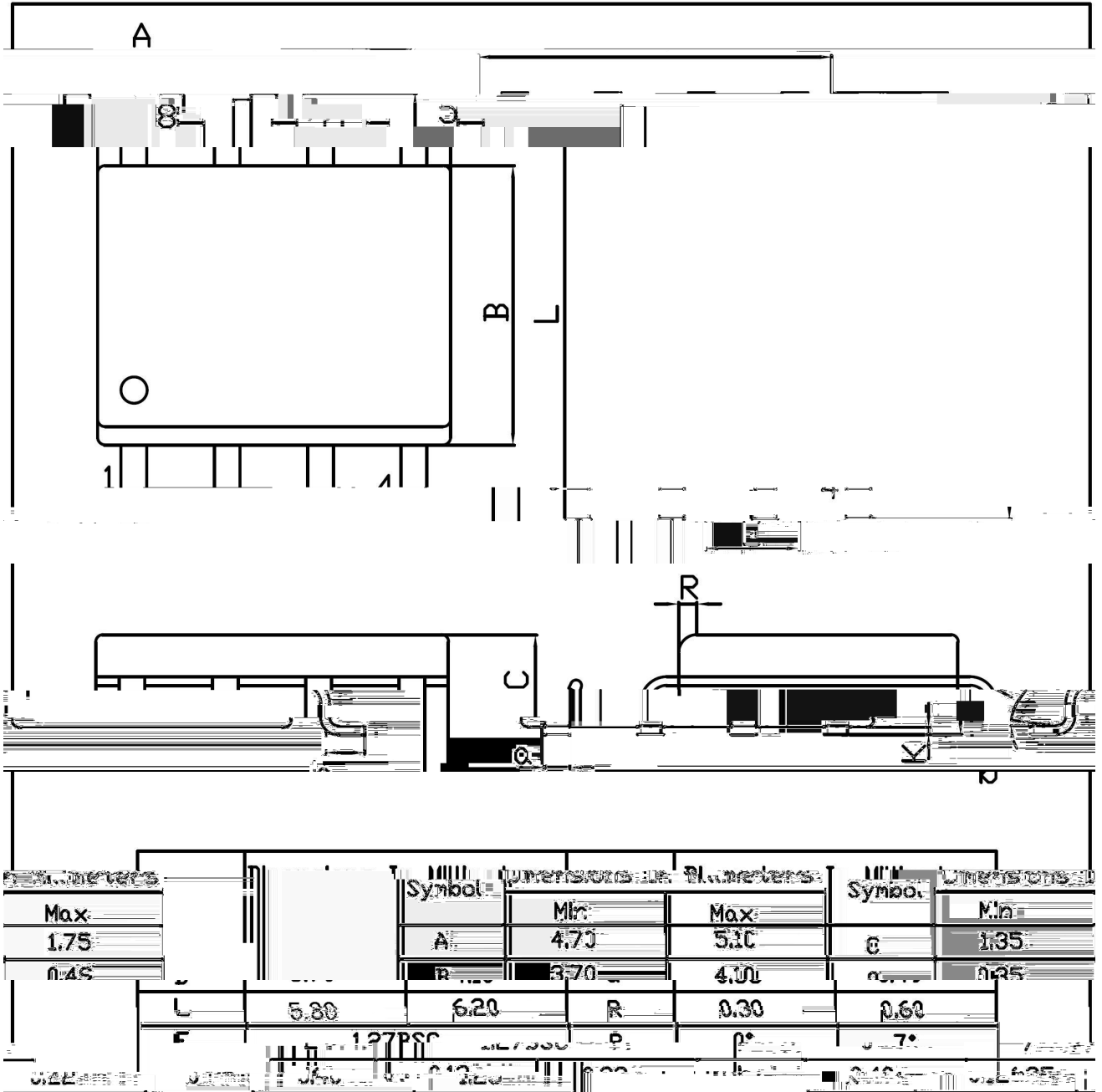




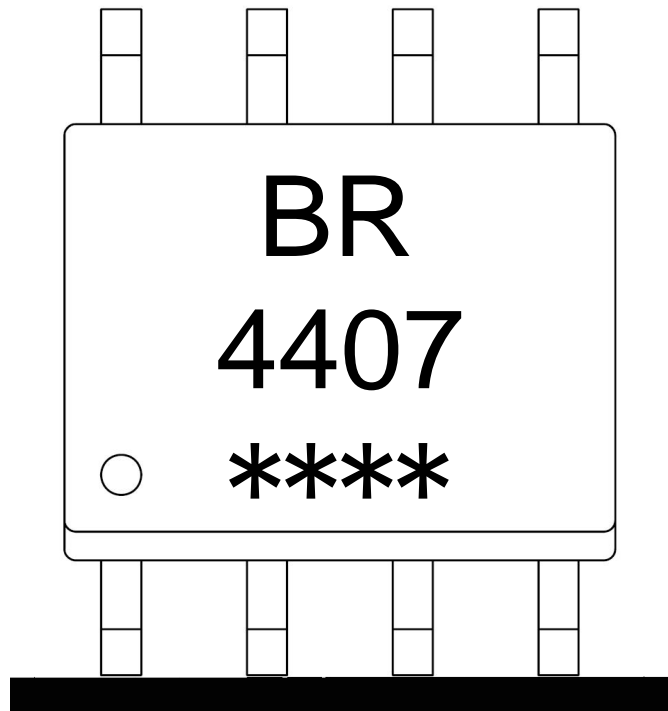
/ Package Dimensions

SOP-8

Unit:mm



/ Marking Instructions



说明：

BR： 为公司代码

4407： 为型号代码

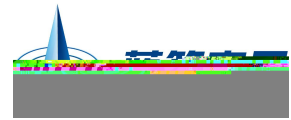
\*\*\*\*： 为生产批号代码，随生产批号变化。

Note:

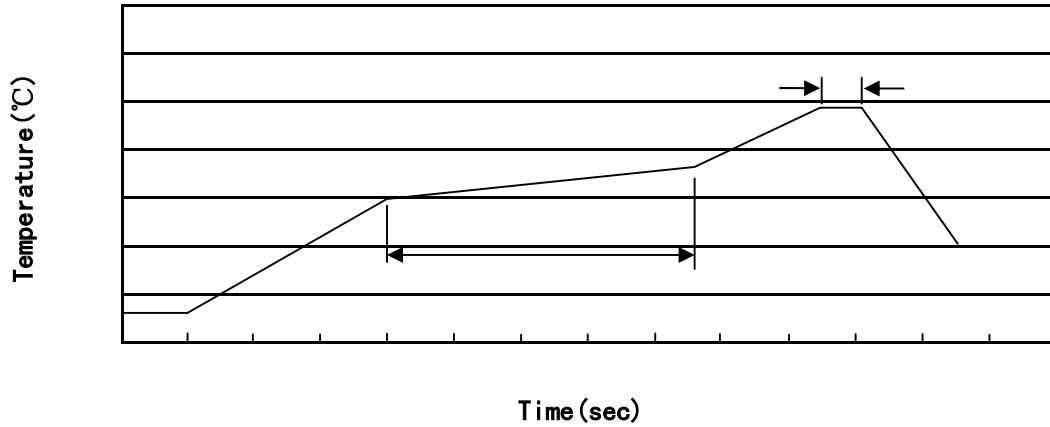
BR: Company Code.

4407: Product Type

\*\*\*\*: Lot No. Code, code change with Lot No.



( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- |   |             |           |  |
|---|-------------|-----------|--|
| 1 | 150 180     | 60 90sec; | 1.Preheating:150~180°C, Time:60~90sec.   |
| 2 | 245±5       | 5±0.5sec; | 2.Peak Temp.:245±5°C, Duration:5±0.5sec. |
| 3 | 2 10°C/sec. |           | 3. Cooling Speed: 2~10°C/sec.            |

/ Resistance to Soldering Heat Test Conditions

260±5°C                      10±1 sec.                      Temp.:260±5°C                      Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOP/ESOP-8	4,000	2	8,000	6	48,000	13" ×12	360×360×50	380×335×366

/ Notices